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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212b8sdfa-v2

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Table 1.2 Specifications for R8C/2A Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART x 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I ² C-bus)
I ² C bus ⁽¹⁾		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution x 12 channels, includes sample and hold function
D/A Converter		8-bit resolution x 2 circuits
Flash Memory		<ul style="list-style-type: none"> • Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 100 times • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 μ A (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 μ A (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽²⁾ -20 to 105°C (Y version) ⁽³⁾
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

Table 1.3 Specifications for R8C/2B Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C/Tiny series core <ul style="list-style-type: none"> • Number of fundamental instructions: 89 • Minimum instruction execution time: <ul style="list-style-type: none"> 50 ns ($f(XIN) = 20$ MHz, $VCC = 3.0$ to 5.5 V) 100 ns ($f(XIN) = 10$ MHz, $VCC = 2.7$ to 5.5 V) 200 ns ($f(XIN) = 5$ MHz, $VCC = 2.2$ to 5.5 V) • Multiplier: 16 bits \times 16 bits \rightarrow 32 bits • Multiply-accumulate instruction: 16 bits \times 16 bits + 32 bits \rightarrow 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM	Refer to Table 1.6 Product List for R8C/2B Group .
Power Supply Voltage Detection	Voltage detection circuit	<ul style="list-style-type: none"> • Power-on reset • Voltage detection 2
I/O Ports	Programmable I/O ports	<ul style="list-style-type: none"> • Input-only: 2 pins • CMOS I/O ports: 55, selectable pull-up resistor • High current drive ports: 8
Clock	Clock generation circuits	3 circuits: XIN clock oscillation circuit (with on-chip feedback resistor), On-chip oscillator (high-speed, low-speed) (high-speed on-chip oscillator has a frequency adjustment function), XCIN clock oscillation circuit (32 kHz) <ul style="list-style-type: none"> • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: <ul style="list-style-type: none"> Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode Real-time clock (timer RE)
Interrupts		<ul style="list-style-type: none"> • External: 5 sources, Internal: 23 sources, Software: 4 sources • Priority levels: 7 levels
Watchdog Timer		15 bits \times 1 (with prescaler), reset start selectable
Timer	Timer RA	8 bits \times 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits \times 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits \times 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits \times 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)
	Timer RE	8 bits \times 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits \times 1 (with capture/compare register pin and compare register pin) Input capture mode, output compare mode

1.2 Product List

Table 1.5 lists Product List for R8C/2A Group, Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/2A Group, Table 1.6 lists Product List for R8C/2B Group, and Figure 1.2 shows a Part Number, Memory Size, and Package of R8C/2B Group.

Table 1.5 Product List for R8C/2A Group

Current of Nov. 2007

Part No.	ROM Capacity	RAM Capacity	Package Type	Remarks		
R5F212A7SNFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	N version		
R5F212A7SNFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A7SNLG	48 Kbytes	2.5 Kbytes	PTLG0064JA-A			
R5F212A8SNFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SNFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212A8SNLG	64 Kbytes	3 Kbytes	PLTG0064JA-A			
R5F212AASNFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASNFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212AASNLG	96 Kbytes	7 Kbytes	PLTG0064JA-A			
R5F212ACSNFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSNFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212ACSNLG	128 Kbytes	7.5 Kbytes	PLTG0064JA-A			
R5F212A7SDFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212A7SDFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A8SDFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SDFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212AASDFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASDFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212ACSDFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSDFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212A7SNXXXFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	N version	Factory programming product ⁽¹⁾	
R5F212A7SNXXXFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A7SNXXXLG	48 Kbytes	2.5 Kbytes	PTLG0064JA-A			
R5F212A8SNXXXFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SNXXXFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212A8SNXXXLG	64 Kbytes	3 Kbytes	PLTG0064JA-A			
R5F212AASNXXXFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASNXXXFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212AASNXXXLG	96 Kbytes	7 Kbytes	PLTG0064JA-A			
R5F212ACSNXXXFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSNXXXFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			
R5F212ACSNXXXLG	128 Kbytes	7.5 Kbytes	PLTG0064JA-A			
R5F212A7SDXXXFP	48 Kbytes	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212A7SDXXXFA	48 Kbytes	2.5 Kbytes	PLQP0064GA-A			
R5F212A8SDXXXFP	64 Kbytes	3 Kbytes	PLQP0064KB-A			
R5F212A8SDXXXFA	64 Kbytes	3 Kbytes	PLQP0064GA-A			
R5F212AASDXXXFP	96 Kbytes	7 Kbytes	PLQP0064KB-A			
R5F212AASDXXXFA	96 Kbytes	7 Kbytes	PLQP0064GA-A			
R5F212ACSDXXXFP	128 Kbytes	7.5 Kbytes	PLQP0064KB-A			
R5F212ACSDXXXFA	128 Kbytes	7.5 Kbytes	PLQP0064GA-A			

NOTE:

1. The user ROM is programmed before shipment.

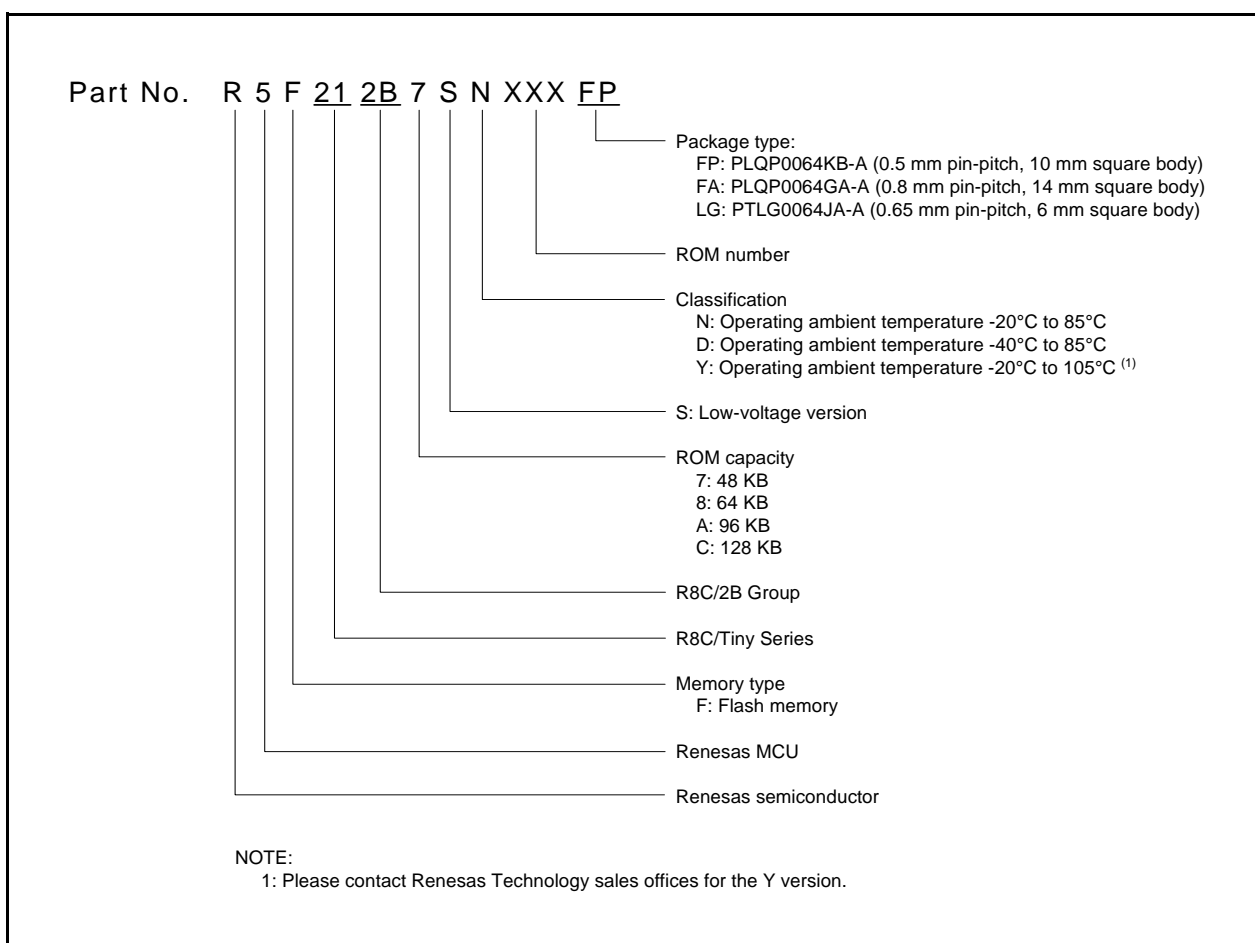


Figure 1.2 Part Number, Memory Size, and Package of R8C/2B Group

1.3 Block Diagram

Figure 1.3 shows a Block Diagram.

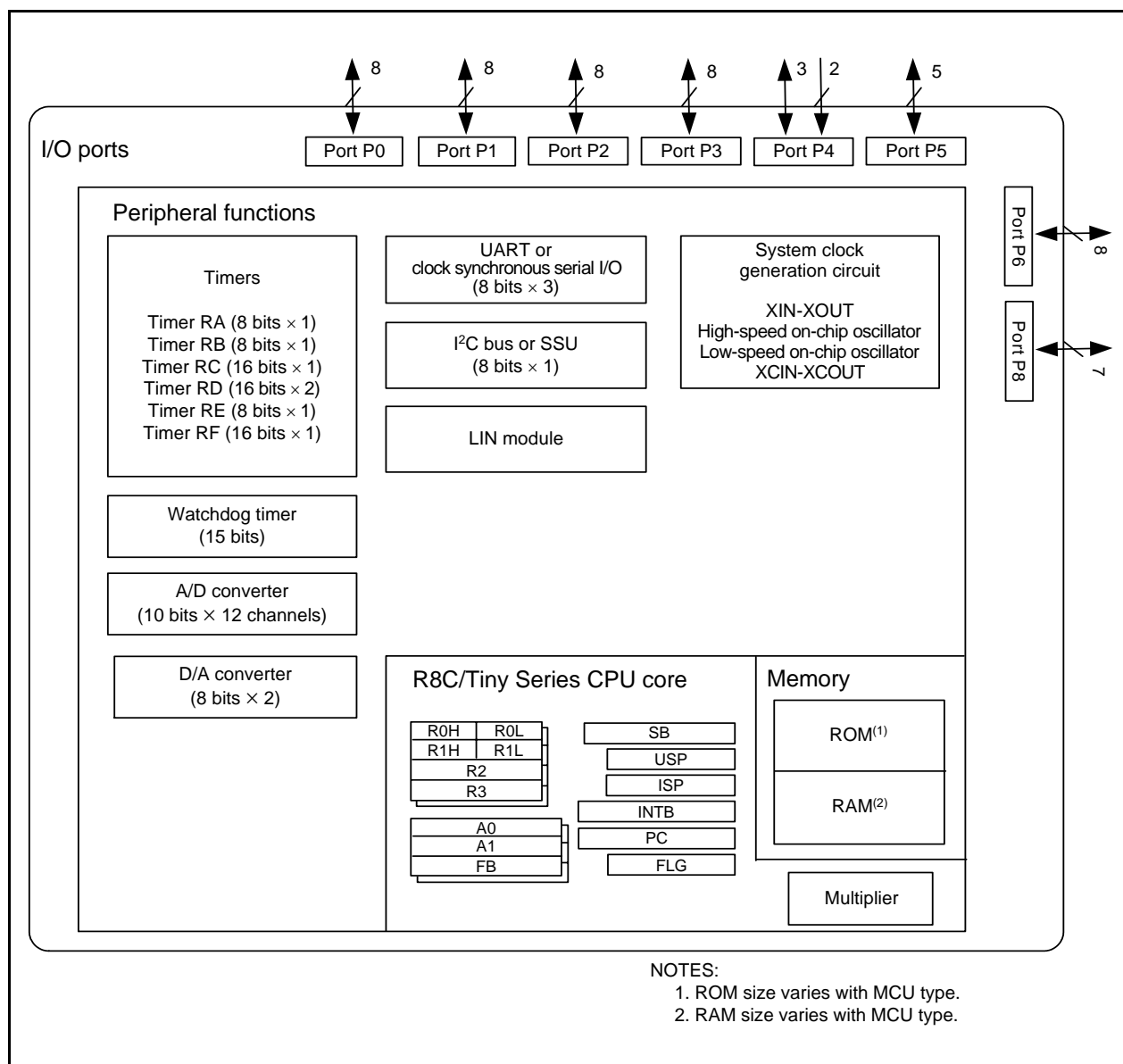


Figure 1.3 Block Diagram

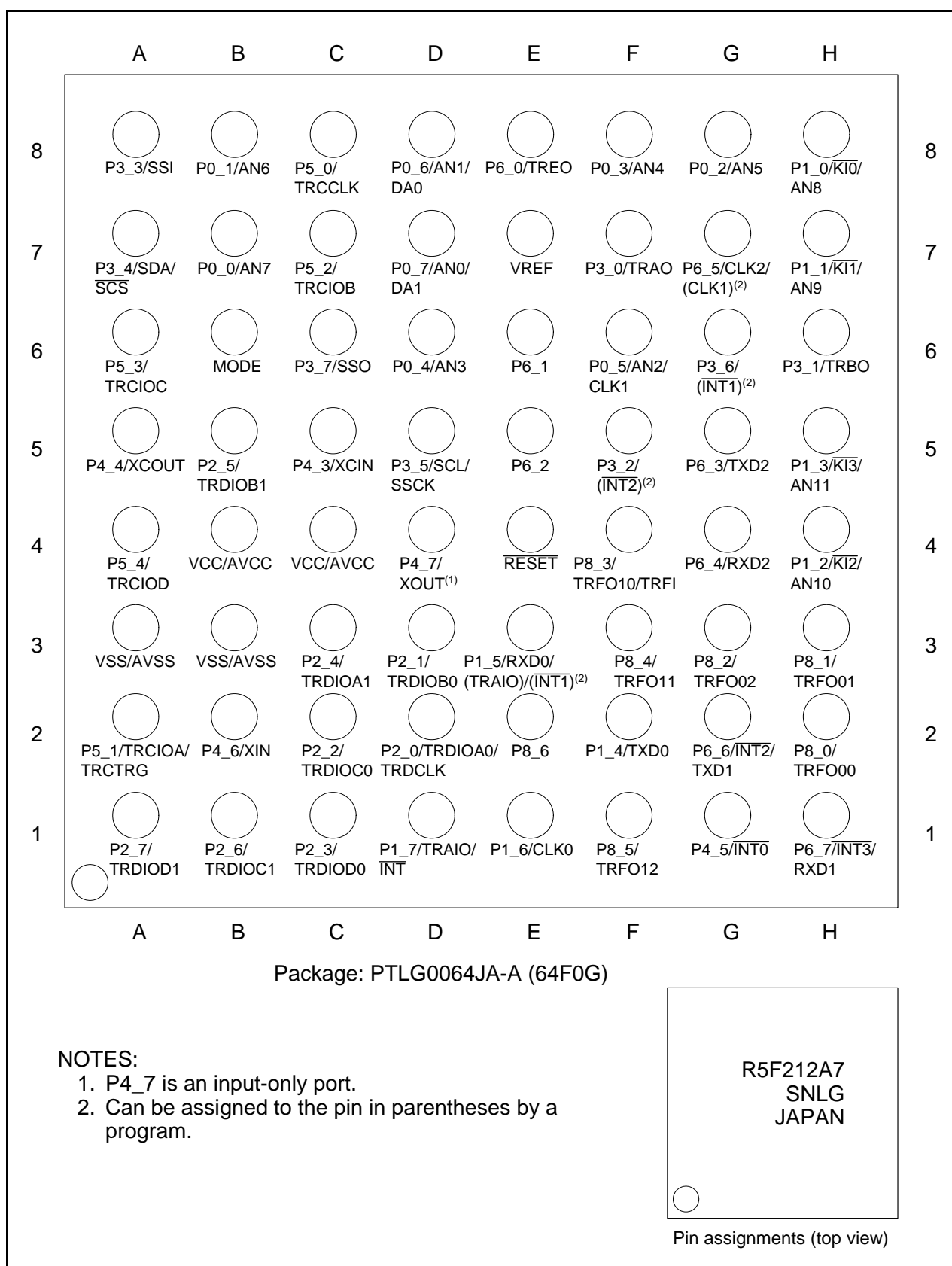


Figure 1.5 64-pin FLGA Package Pin Assignment (Top Perspective View)

Table 1.8 Pin Name Information by Pin Number (2)

Pin Number	Control Pin	Port	I/O Pin Functions for of Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter
46		P1_3	$\overline{\text{KI3}}$					AN11
47		P1_2	$\overline{\text{KI2}}$					AN10
48		P1_1	$\overline{\text{KI1}}$					AN9
49		P1_0	$\overline{\text{KI0}}$					AN8
50		P0_0						AN7
51		P0_1						AN6
52		P0_2						AN5
53		P0_3						AN4
54		P0_4						AN3
55		P6_2						
56		P6_1						
57		P0_5			CLK1			AN2
58		P0_6						AN1/DA0
59	VSS/AVSS							
60		P0_7						AN0/DA1
61	VREF							
62	VCC/AVCC							
63		P3_7				SSO		
64		P3_5				SSCK	SCL	

Table 1.10 Pin Functions (2)

Item	Pin Name	I/O Type	Description
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
D/A converter	DA0 to DA1	O	D/A converter output pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_5, P5_0 to P5_4, P6_0 to P6_7, P8_0 to P8_6	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P2_0 to P2_7 also function as LED drive ports.
Input port	P4_6, P4_7	I	Input-only ports

I: Input O: Output I/O: Input and output

Table 4.5 SFR Information (5)⁽¹⁾

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h	LIN Control Register 2	LINCR2	00h
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRE	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Clock Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011111b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h			
0134h			
0135h			
0136h			
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h

NOTE:

1. The blank regions are reserved. Do not access locations in these regions

Table 4.9 SFR Information (9)⁽¹⁾

Address	Register	Symbol	After reset
0200h			
0201h			
0202h			
0203h			
0204h			
0205h			
0206h			
0207h			
0208h			
0209h			
020Ah			
020Bh			
020Ch			
020Dh			
020Eh			
020Fh			
0210h			
0211h			
0212h			
0213h			
0214h			
0215h			
0216h			
0217h			
0218h			
0219h			
021Ah			
021Bh			
021Ch			
021Dh			
021Eh			
021Fh			
0220h			
0221h			
0222h			
0223h			
0224h			
0225h			
0226h			
0227h			
0228h			
0229h			
022Ah			
022Bh			
022Ch			
022Dh			
022Eh			
022Fh			
0230h			
0231h			
0232h			
0233h			
0234h			
0235h			
0236h			
0237h			
0238h			
0239h			
023Ah			
023Bh			
023Ch			
023Dh			
023Eh			
023Fh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.10 SFR Information (10)(1)

Address	Register	Symbol	After reset
0240h			
0241h			
0242h			
0243h			
0244h			
0245h			
0246h			
0247h			
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h			
0271h			
0272h			
0273h			
0274h			
0275h			
0276h			
0277h			
0278h			
0279h			
027Ah			
027Bh			
027Ch			
027Dh			
027Eh			
027Fh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage			2.2	–	5.5	V
V _{SS} /AV _{SS}	Supply voltage			–	0	–	V
V _{IH}	Input “H” voltage			0.8 V _{CC}	–	V _{CC}	V
V _{IL}	Input “L” voltage			0	–	0.2 V _{CC}	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)		–	–	–240	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)		–	–	–120	mA
I _{OH} (peak)	Peak output “H” current	Except P2_0 to P2_7		–	–	–10	mA
		P2_0 to P2_7		–	–	–40	mA
I _{OH} (avg)	Average output “H” current	Except P2_0 to P2_7		–	–	–5	mA
		P2_0 to P2_7		–	–	–20	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)		–	–	240	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)		–	–	120	mA
I _{OL} (peak)	Peak output “L” current	Except P2_0 to P2_7		–	–	10	mA
		P2_0 to P2_7		–	–	40	mA
I _{OL} (avg)	Average output “L” current	Except P2_0 to P2_7		–	–	5	mA
		P2_0 to P2_7		–	–	20	mA
f(XIN)	XIN clock input oscillation frequency		3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
f(XCIN)	XCIN clock input oscillation frequency		2.2 V ≤ V _{CC} ≤ 5.5 V	0	–	70	kHz
–	System clock	OCD2 = 0 XIN clock selected	3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
		OCD2 = 1 On-chip oscillator clock selected	FRA01 = 0 Low-speed on-chip oscillator clock selected	–	125	–	kHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 3.0 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	10	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.2 V ≤ V _{CC} ≤ 5.5 V	–	–	5	MHz

NOTES:

1. V_{CC} = 2.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.

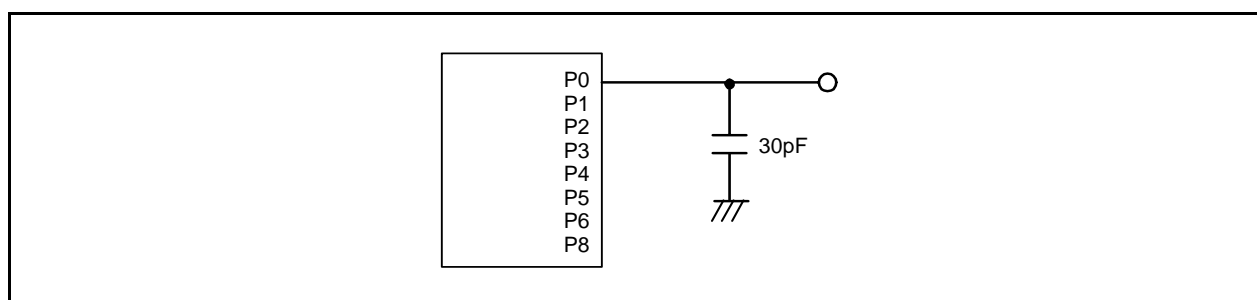
**Figure 5.1 Ports P0 to P6, P8 Timing Measurement Circuit**

Table 5.16 Electrical Characteristics (1) [V_{CC} = 5 V]

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μ A	V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μ A	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μ A	—	—	0.45	V
		P2_0 to P2_7	Drive capacity HIGH I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μ A	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{TRFI}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{CLK2}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$		0.1	0.5	—	V
		$\overline{\text{RESET}}$		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V	—	—	5.0	μ A
I _{IL}	Input "L" current		V _I = 0 V	—	—	-5.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V	30	50	167	k Ω
R _{IXIN}	Feedback resistance	XIN		—	1.0	—	M Ω
R _{IXCIN}	Feedback resistance	XCIN		—	18	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

NOTE:

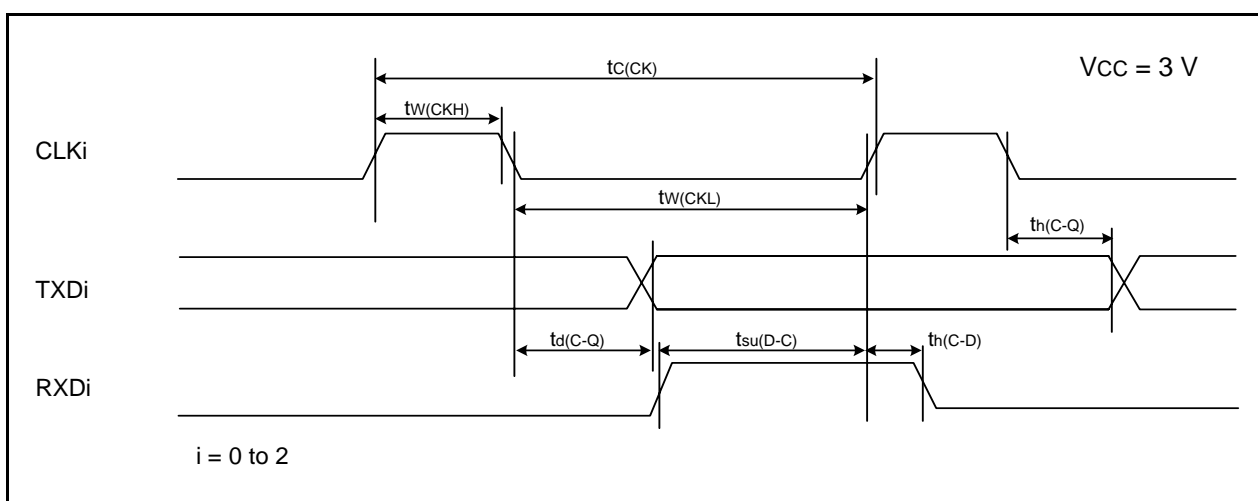
- V_{CC} = 4.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.24 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
Icc	Power supply current (Vcc = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.5	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	5.5	11	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	–	145	400	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	–	145	400	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	–	30	–	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	28	85	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	17	50	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (high drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	3.3	–	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (low drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	2.1	–	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	0.65	3.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	1.65	–	μA

Table 5.28 Serial Interface

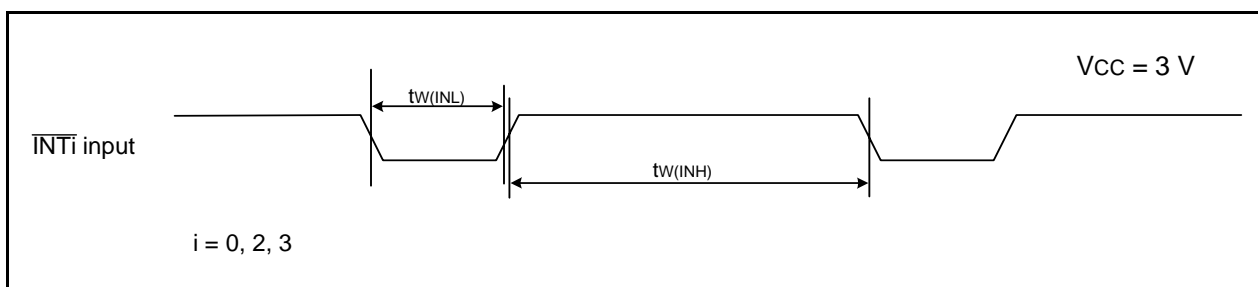
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi Input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.16 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.29 External Interrupt \overline{INTi} ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	380 ⁽²⁾	—	ns

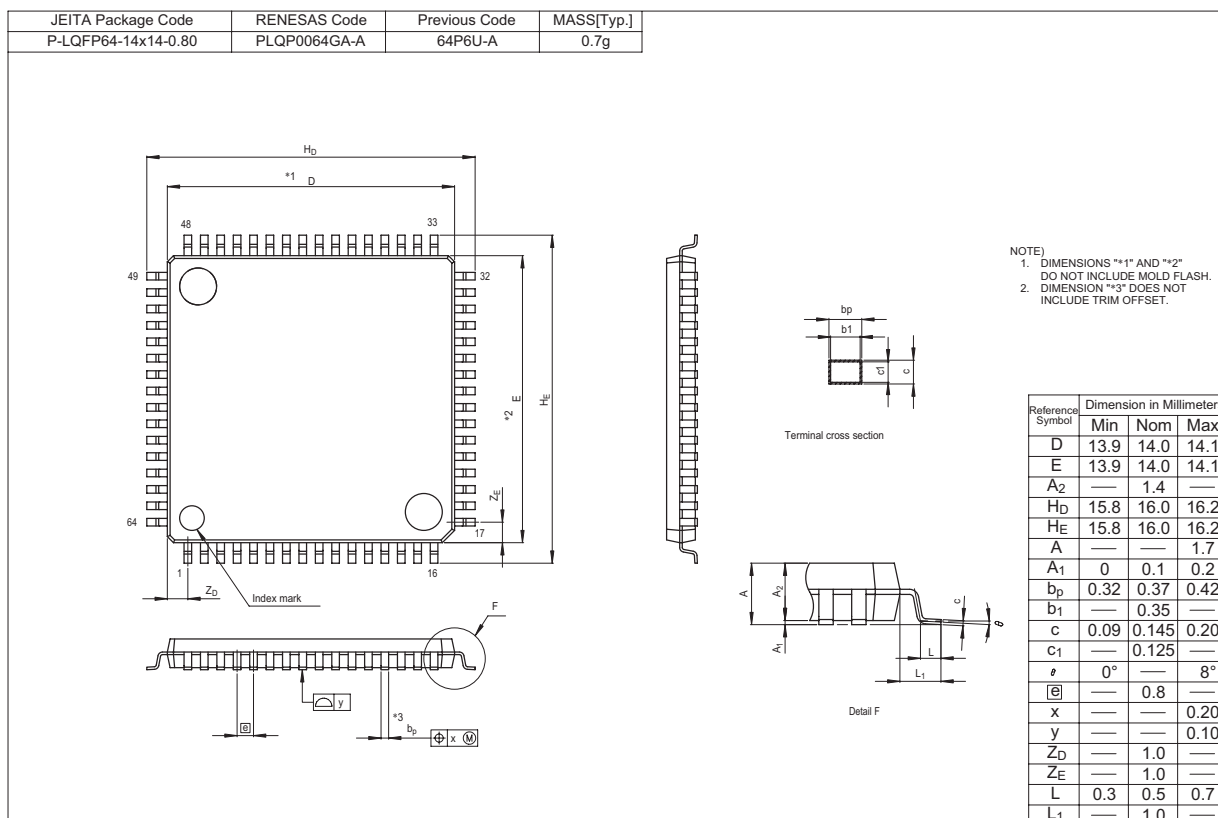
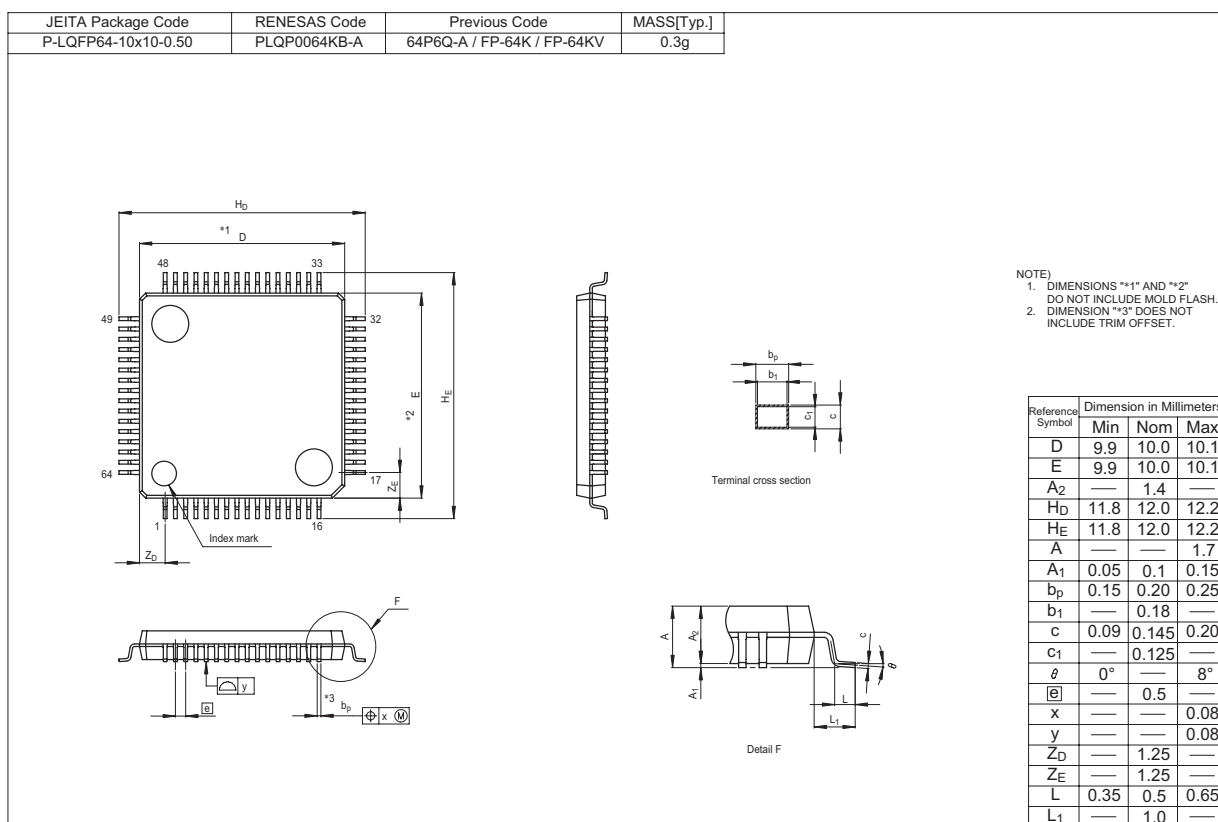
NOTES:

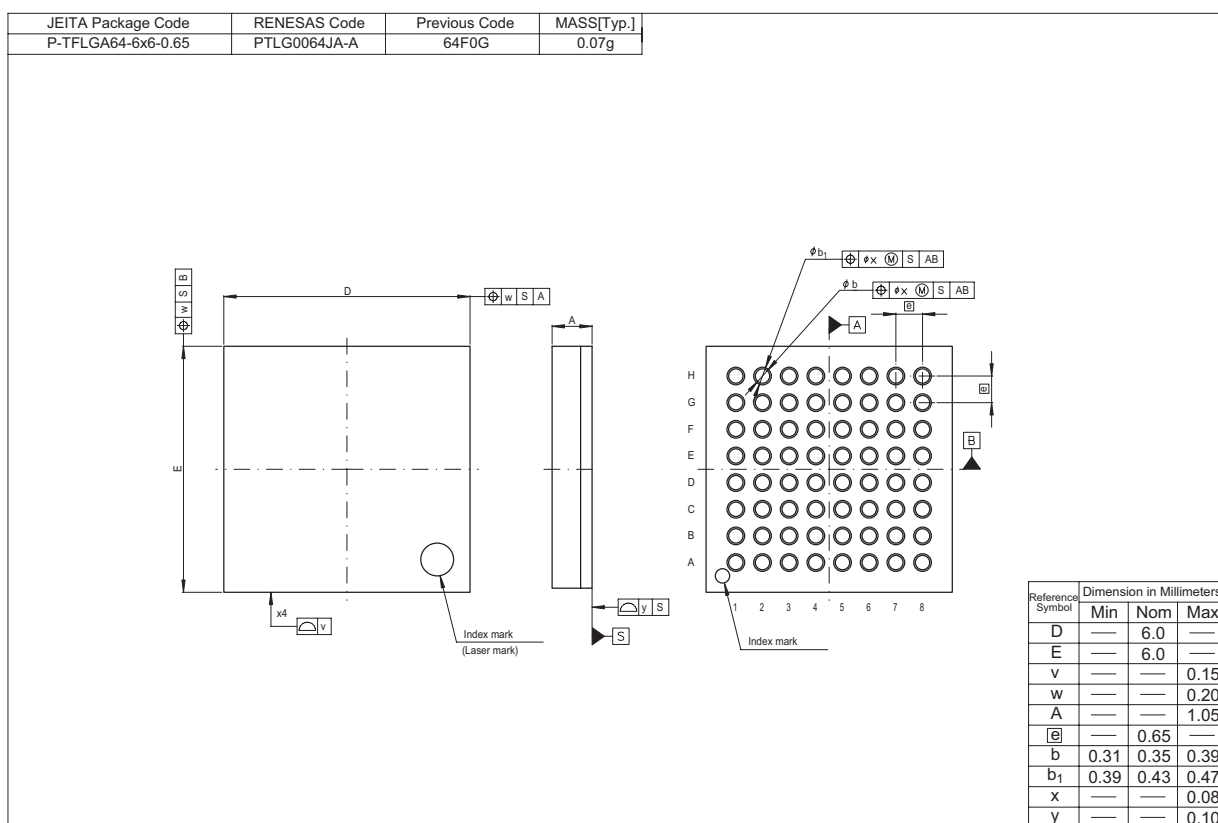
1. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input HIGH width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input LOW width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.

**Figure 5.17 External Interrupt \overline{INTi} Input Timing Diagram when Vcc = 3 V**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.





REVISION HISTORY	R8C/2A Group, R8C/2B Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.30	Dec 22, 2006	19	Table 4.1; • 000Ah: "00XXX000b" → "00h" revised • 0008h: "Module Standby Control Register" → "Module Operation Enable Register" revised • 000Fh: "00011111b" → "00X11111b" revised
		37	Table 5.11 revised
1.00	Feb 09, 2007	All pages	"Preliminary" deleted
		3	Table 1.2 revised
		5	Table 1.4 revised
		6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised
		19	Table 4.1; • 0008h: "Module Standby Control Register" → "Module Operation Enable Register" revised • 000Ah: "00XXX000b" → "00h" revised • 000Fh: "00011111b" → "00X11111b" revised • 002Bh: "High-Speed On-Chip Oscillator Control Register 6" added
		23	Table 4.5; 0105h: "LIN Control Register 2" register name revised
		31	Table 5.2 revised
		32	Table 5.3 and Table 5.4; NOTE1 revised
		37	Table 5.11 revised
		44	Table 5.17 revised
		46	Table 5.21 and Figure 5.11; "i = 0 to 2" revised
		48	Table 5.24 revised
		50	Table 5.28 revised, Figure 5.16 "i = 0 to 2" revised
		52	Table 5.31 revised
		53	Table 5.34 revised
		54	Table 5.35 and Figure 5.21; "i = 0 to 2" revised
2.00	Oct 17, 2007	All pages	"PTLG0064JA-A (64F0G) package" added
		3, 5	Table 1.2 and Table 1.4; • Operating Ambient Temperature: Y version added • Package: 64-pin FLGA added
		6 to 7	Table 1.5 and Figure 1.1 revised
		8	Table 1.6 and Figure 1.2 revised
		10	Figure 1.4 "64-pin LQFP Package" added
		11	Figure 1.5 added
		19 to 20	Figure 3.1 and Figure 3.2 revised
		24	Table 4.4; 00F5h: "00h" → "000000XXb" revised

Notes:

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